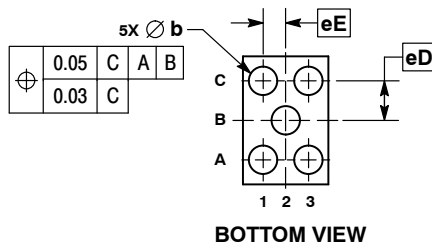
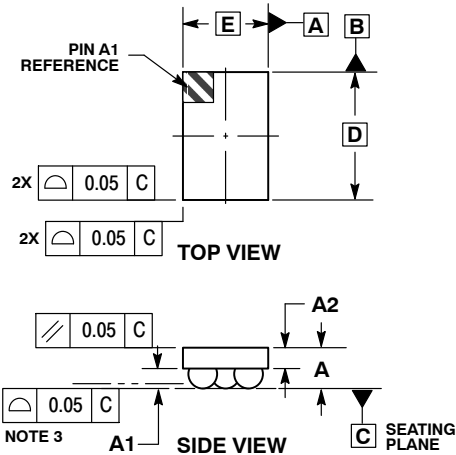




SCALE 4:1

WLCSP5, 1.41x0.94
CASE 567LT
ISSUE 0

DATE 05 JUN 2015


NOTES:

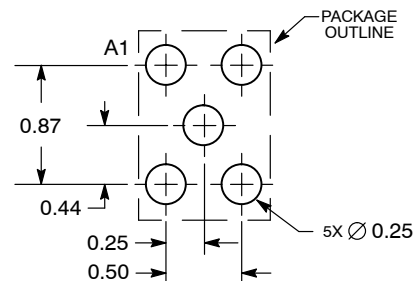
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.40	0.50
A1	0.21	0.27
A2	0.23	REF
b	0.29	0.35
D	1.41	BSC
E	0.94	BSC
eD	0.435	BSC
eE	0.25	BSC

GENERIC MARKING DIAGRAM*


X = Specific Device Code
M = Month Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*


DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	WLCSP5, 1.41X0.94	PAGE 1 OF 1

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